

# Global Wireless Chipsets Market 2022-2028

<https://marketpublishers.com/r/G09667837407EN.html>

Date: November 2022

Pages: 78

Price: US\$ 2,850.00 (Single User License)

ID: G09667837407EN

## Abstracts

A wireless chipset is a piece of internal hardware designed to allow a device to communicate with another wireless-enabled device. The global wireless chipsets market is expected to increase by USD 4.7 billion, at a compound annual growth rate (CAGR) of 8.3% from 2022 to 2028, according to the latest edition of the Global Wireless Chipsets Market Report.

The report covers market size and growth, segmentation, regional breakdowns, competitive landscape, trends and strategies for global wireless chipsets market. It traces the market's historic and forecast market growth. The report identifies top segments for opportunities and strategies based on market trends and leading competitors' approaches. This study also provides an analysis of the impact of the COVID-19 crisis on the wireless chipsets industry.

This industry report offers market estimates and forecasts of the global market, followed by a detailed analysis of the product, end user, and region. The global market for wireless chipsets can be segmented by product: Bluetooth standalone, low-power wireless IC, Wi-Fi and Bluetooth combo, Wi-Fi standalone. The low-power wireless IC segment captured the largest share of the market in 2021. Wireless chipsets market is further segmented by end user: automotive, consumer electronics, enterprise, industrial, mobile handsets, others. The mobile handsets segment held the largest share of the global wireless chipsets market in 2021 and is anticipated to hold its share during the forecast period. Based on region, the wireless chipsets market is segmented into: Asia Pacific, Europe, North America, Rest of the World (RoW). In 2021, North America made up the largest share of revenue generated by the wireless chipsets market.

## Market Segmentation

By product: Bluetooth standalone, low-power wireless IC, Wi-Fi and Bluetooth combo,

## Wi-Fi standalone

By end user: automotive, consumer electronics, enterprise, industrial, mobile handsets, others

By region: Asia Pacific, Europe, North America, Rest of the World (RoW)

The report also provides a detailed analysis of several leading wireless chipsets market vendors that include Broadcom Inc., HiSilicon Technology Co., Ltd., Infineon Technologies AG, Intel Corporation, MediaTek Inc., Microchip Technology Inc., NXP Semiconductors N.V., ON Semiconductor Corporation (onsemi), Qorvo, Inc., Qualcomm Incorporated, Realtek Semiconductor Corp., Skyworks Solutions, Inc., STMicroelectronics N.V., Texas Instruments Incorporated, Tsinghua Unigroup Co., Ltd., among others.

**\*REQUEST FREE SAMPLE TO GET A COMPLETE LIST OF COMPANIES**

## Historical & Forecast Period

This research report provides analysis for each segment from 2018 to 2028 considering 2021 to be the base year.

## Scope of the Report

To analyze and forecast the market size of the global wireless chipsets market.

To classify and forecast the global wireless chipsets market based on product, end user, region.

To identify drivers and challenges for the global wireless chipsets market.

To examine competitive developments such as mergers & acquisitions, agreements, collaborations and partnerships, etc., in the global wireless chipsets market.

To identify and analyze the profile of leading players operating in the global wireless chipsets market.

## Why Choose This Report

Gain a reliable outlook of the global wireless chipsets market forecasts from 2022 to 2028 across scenarios.

Identify growth segments for investment.

Stay ahead of competitors through company profiles and market data.

The market estimate for ease of analysis across scenarios in Excel format.

Strategy consulting and research support for three months.

Print authentication provided for the single-user license.

## Contents

### **PART 1. INTRODUCTION**

Report description  
Objectives of the study  
Market segment  
Years considered for the report  
Currency  
Key target audience

### **PART 2. METHODOLOGY**

### **PART 3. EXECUTIVE SUMMARY**

### **PART 4. MARKET OVERVIEW**

Introduction  
Drivers  
Restraints  
Impact of COVID-19 pandemic

### **PART 5. MARKET BREAKDOWN BY PRODUCT**

Bluetooth standalone  
Low-power wireless IC  
Wi-Fi and Bluetooth combo  
Wi-Fi standalone

### **PART 6. MARKET BREAKDOWN BY END USER**

Automotive  
Consumer electronics  
Enterprise  
Industrial  
Mobile handsets  
Others

### **PART 7. MARKET BREAKDOWN BY REGION**

Asia Pacific

Europe

North America

Rest of the World (RoW)

## **PART 8. KEY COMPANIES**

Broadcom Inc.

HiSilicon Technology Co., Ltd.

Infineon Technologies AG

Intel Corporation

MediaTek Inc.

Microchip Technology Inc.

NXP Semiconductors N.V.

ON Semiconductor Corporation (onsemi)

Qorvo, Inc.

Qualcomm Incorporated

Realtek Semiconductor Corp.

Skyworks Solutions, Inc.

STMicroelectronics N.V.

Texas Instruments Incorporated

Tsinghua Unigroup Co., Ltd.

**\*REQUEST FREE SAMPLE TO GET A COMPLETE LIST OF COMPANIES**

**DISCLAIMER**

## I would like to order

Product name: Global Wireless Chipsets Market 2022-2028

Product link: <https://marketpublishers.com/r/G09667837407EN.html>

Price: US\$ 2,850.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

[info@marketpublishers.com](mailto:info@marketpublishers.com)

## Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/G09667837407EN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:  
Last name:  
Email:  
Company:  
Address:  
City:  
Zip code:  
Country:  
Tel:  
Fax:  
Your message:

**\*\*All fields are required**

Customer signature \_\_\_\_\_

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970